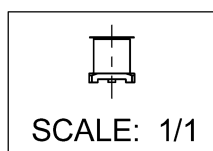
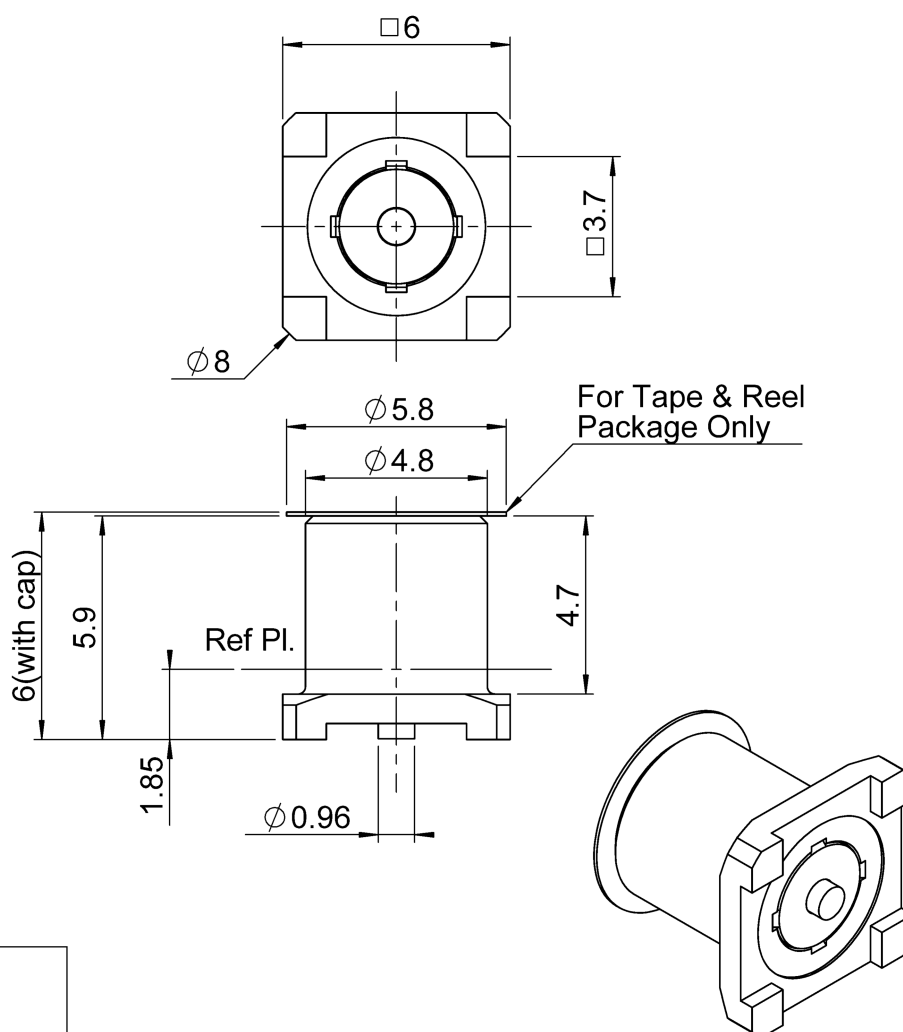


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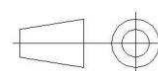
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All dimensions are in mm.



COMPONENTS	MATERIALS	PLATING (μm)
Body	<b>BRASS</b>	<b>NPGR</b>
Center contact	<b>BERYLLIUM COPPER</b>	<b>NPGR</b>
Outer contact		
Insulator	<b>PTFE</b>	
Gasket		
Others parts	<b>POLYIMIDE FILM</b>	
-	-	-
-	-	-

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## PACKAGING

Standard	Unit	Other
<b>500</b>	<b>Contact us</b>	<b>Contact us</b>

## ELECTRICAL CHARACTERISTICS

Impedance		<b>50</b>	Ω
Frequency		<b>0-6</b>	GHz
VSWR	<b>1.05</b>	<b>+</b>	<b>0.0500</b> x F(GHz) Maxi
Insertion loss		<b>0.03</b>	√F(GHz) dB Maxi
RF leakage	- (	<b>NA</b>	- F(GHz)) dB Maxi
Voltage rating		<b>335</b>	Veff Maxi
Dielectric withstanding voltage		<b>1000</b>	Veff mini
Insulation resistance		<b>1000</b>	MΩ mini

## ENVIRONMENTAL

Operating temperature	<b>-55/+155</b>	°C
Hermetic seal	<b>NA</b>	Atm.cm3/s
Panel leakage	<b>NA</b>	

## MECHANICAL CHARACTERISTICS

Center contact retention		
Axial force – Mating End	<b>10</b>	N mini
Axial force – Opposite end	<b>10</b>	N mini
Torque	<b>NA</b>	N.cm mini

## SPECIFICATION

## OTHER CHARACTERISTICS

Recommended torque		
Mating	<b>NA</b>	N.cm
Panel nut	<b>NA</b>	N.cm

Assembly instruction:

Mating life	<b>100</b>	Cycles mini
Weight	<b>0.6080</b>	g

Others:

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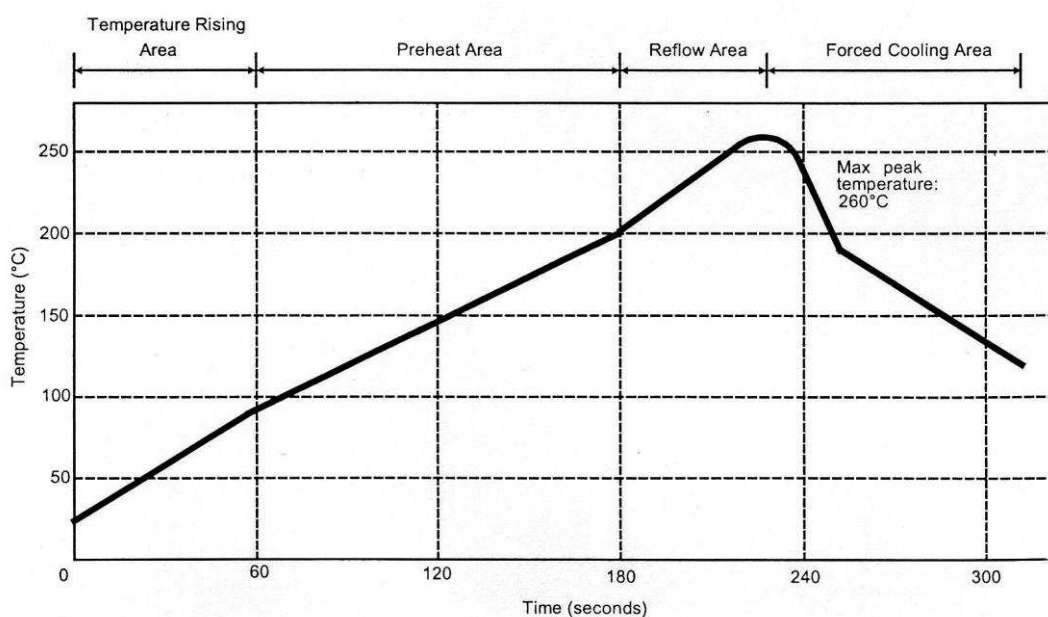
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## SOLDER PROCEDURE OF MCX RECEPTACLE IN INDUSTRIAL ENVIRONMENT

1. Deposit solder paste 'Sn95 Ag4 Cu0.5' on mounting zone by screen printing application.  
We recommend a low residue flux.  
We advise a thickness of 150 micromm ( 5.850 microinch ). Verify that the edges of the zone are clean.
2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.  
A video camera is recommended for positioning of the component.  
Adhesive agents must not be used on the receptacle.
3. This process of soldering has been tested with convection oven.  
Below please find, the typical profile to use.
4. The cleaning of printed circuit boards is not obliged.
5. Verification of solder joints and position of the component by visual inspection.

### TEMPERATURE PROFIL



Parmeter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

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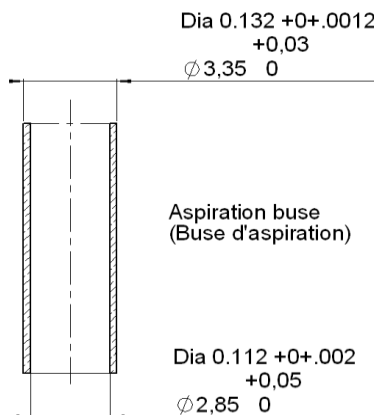
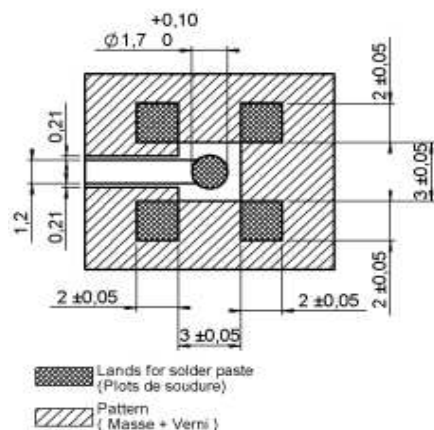
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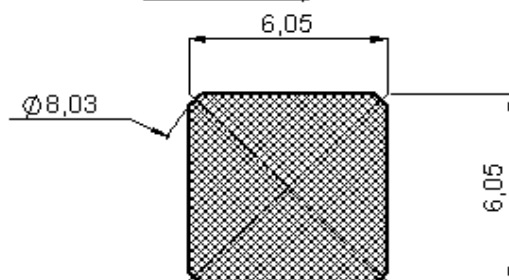
## MCX SERIES – INFORMATION

Coplanar line : pattern and signal are on the same side. Thickness of PCB : 1.6 mm

The material of PCB is the epoxy resin of glass fabrics bacs. ( $\epsilon_r=4,8$ ). The solder resist should be printed except for the land pattern on the PCB.



SHADOW OF RECEPTACLE  
FOR VIDEO CAMERA  
(Ombre de l'embase pour  
camera video)



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